

ABSTRACT

[Problem] To provide an adhesive composition which is used for fixing a semiconductor wafer or the like onto a substrate, exhibits firm adhesion with high heat resistance in the wafer grinding stage and is melted by heating to enable easy peeling after the completion of the wafer grinding stage. [Means to solve problem] The hot-melt adhesive composition of the invention is a composition containing as a main component a crystalline compound having a melting temperature of 50 to 300°C, and has a melting temperature width of not more than 30°C and a melt viscosity of not more than 0.1 Pa·s. The crystalline compound as a main component is desired to be an organic compound composed of elements of C, H and O only and having a molecular weight of not more than 1000, preferably an aliphatic compound or an alicyclic compound, particularly preferably a compound having a steroid skeleton and/or a hydroxyl group.